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Orderable: N/A	Designed for: Public Release	Mod. Date: 6/6/2016	
TID #: 00887	Project Title: USB2.0 Short-to-battery Tolerant Hub with 2.4A CD	Sheet: 2 of 3	
Number: TIDA-00887	Rev: E1	Assembly Variant: 001	Size: B
SVN Rev: Not in version control	File: TIDA-00887_Sch.SchDoc	Engineer: Guy Yater	Contact: http://www.ti.com/support





PCB Number: TIDA-00887
PCB Rev: E1

PCB
LOGO
Logo2

PCB
LOGO
Pb-Free Symbol

A You should delete the nylon screws/standoffs and/or the bumpons as needed for your design (or substitute other parts from Hardware.IntLib). Bumpons are cheaper, but provide less clearance.

Deleting anything else from this page may result in your EVM submission being rejected (until you add them back).


Update the Label Text in the Label Table as needed for each Assembly Variant.

You can delete this note too.

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

Orderable: N/A	Designed for: Public Release	Mod. Date: 5/27/2016	
TID #: 00887	Project Title: USB2.0 Short-to-battery Tolerant Hub with 2.4A CD		
Number: TIDA-00887	Rev: E1	Sheet: 3 of 3	
SVN Rev: Not in version control	Assembly Variant: 001	File: TIDA-00887_Hardware.SchDoc	
Drawn By:	Engineer: Guy Yater	Contact: http://www.ti.com/support	Size: B
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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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